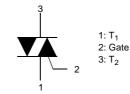


FKN1N60SA TRIAC (Silicon Bidirectional Thyristor)

Application Explanation

- Switching mode power supply, light dimmer, electric flasher unit, hair drier
- TV sets, stereo, refrigerator, washing machine
- Electric blanket, solenoid driver, small motor control
- Photo copier, electric tool





Absolute Maximum Ratings $T_a = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value		Rating	Units
V _{DRM} V _{RRM}	Peak Repetitive Off-State Voltage	Sine Wave 50 to 60Hz, Gate Open		600	V
I _{T (RMS)}	RMS On-State Current	Commercial frequency, sine full wave 360° conduction, Tc= 70 $^\circ\!\mathbb{C}$		1.0	A
I _{TSM}	SM Surge On-State Current Sinewave 1 full cycle, peak valu		50Hz	9	А
		non-repetitive 60Hz		10	А
l ² t	I ² t for Fusing	Value corresponding to 1 cycle of halfwave, surge on-state current, tp=8.4ms		0.41	A ² s
P _{GM}	Peak Gate Power Dissipation			5	W
P _{G (AV)}	Average Gate Power Dissipation			0.1	W
V _{GM} Peak Gate Voltage				5	V
I _{GM}	Peak Gate Current			1	А
TJ	Junction Temperature			- 40 ~ 125	°C
T _{STG}	Storage Temperature			- 40 ~ 125	°C

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case (note1)	40	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient (note2)	160	°C/W

Note1: Infinite cooling condition.

Note2: JESD51-10 (Test Borad: FR4 3.0"*4.5"*0.062", Minimum land pad)

August 2006

FKN1N60SA
TRIAC (S
(Silicon B
Bidirectional Th
l Thyristor)

Electrical Characteristics T_c = 25°C unless otherwise noted

Symbol	Parameter		Test Condition		Min.	Тур.	Max.	Units
I _{DRM} I _{RRM}	Repetieive Peak Off-State Current		V _{DRM} /V _{RRM} applied		-	-	100	μA
V _{TM}	On-State Voltage		T _C =25°C, I _{TM} =1.12A Instantaneous measurement		-	-	1.8	V
		Ι		T2(+), Gate (+)	-	-	2.0	V
V _{GT}	Gate Trigger Voltage	П	V _D =12V, R _L =100Ω	T2(+), Gate (-)	-	-	2.0	V
		III		T2(-), Gate (-)	-	-	2.0	V
	Gate Trigger Current	Ι		T2(+), Gate (+)	-	-	5	mA
I _{GT}		П	V _D =12V, R _L =100Ω	T2(+), Gate (-)	-	-	5	mA
		III		T2(-), Gate (-)	-	-	5	mA
V _{GD}	Gate Non-Trigger Voltage		T _J =125°C, V _D =1/2V _{DRM}		0.2	-	-	V
I _H	Holding Current (I, II, III)		V _D = 12V, I _{TM} = 200mA		-	-	15	mA
ΙL	Latching Current I, III		$V_{\rm D} = 12V, I_{\rm G} = 10mA$		-	-	15	mA
		П			-	-	20	mA
dv/dt(s)	Critical Rate of Rise of Off-State Voltag		V _{DRM} = 63% Rated, T _j = 125°C, Exponential Rise		20	-	-	V/µs
dv/dt(c)	Critical-Rate of Rise of Off-State Com- mutating Voltage (di/dt=-0.7A/uS)				3.0	-	-	V/µs

Commutation dv/dt test

Device	Test Condition	Commutating voltage and current waveforms (inductive load)
FKN1N60SA	 Junction Temperature T_J=125°C Rate of decay of on-state commutating current (di/dt)_C Peak off-state voltage V_D = 300V 	Supply Voltage Time Main Current Time Main Voltage V _D



Quadrant Definitions for a Triac T2 Positive (+) T2 (+) T2 (-) I_{GT} Quadrant II (+) I_{GT} Quadrant I T1 Τ1 + I_{GT} I_{GT} -(-) T2 (-) T2 (+) I_{GT} (-) I_{GT} Quadrant III Quadrant IV Т1 T1

Package Marking and Ordering Information

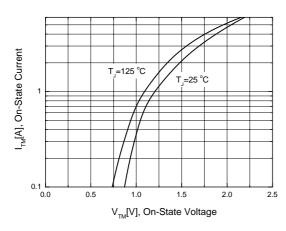
Device Marking	Device	Package	Packing	Tape Width	Quantity
K1N60SA	FKN1N60SA	TO-92	Bulk		

T2 Negative

Typical Performance Characteristics

Figure 1. On-State Characteristics





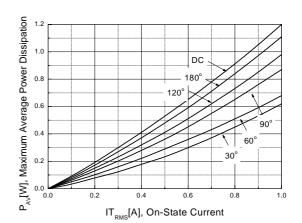


Figure 3. RMS Current Rating

Figure 4. Typical Gate Trigger Current vs Junction Temperature

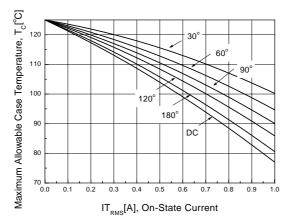


Figure5. Typical Gate Voltage vs Junction Temperarure

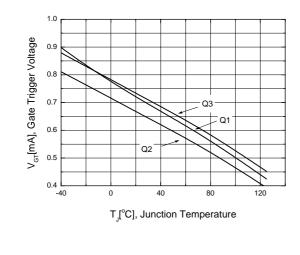


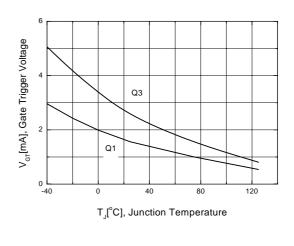
Figure6. Typical Latching Currrent vs Junction Temperature

40

T [°C], Junction Temperature

80

120



I_{GT}[mA], Gate Trigger Current

2

0 L -40 Q3

Q2

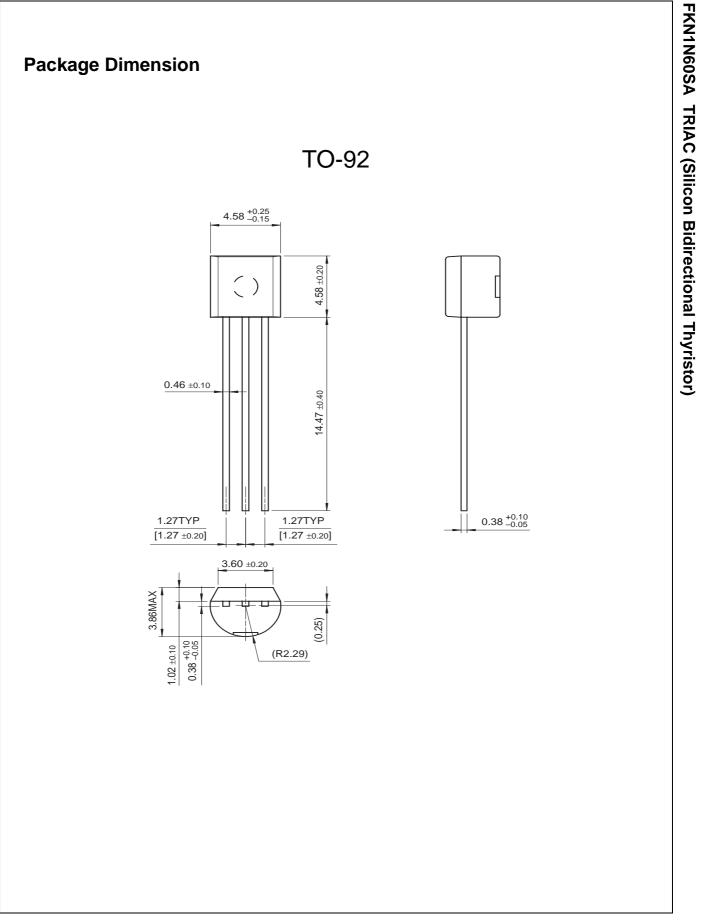
Q1

0

Typical Performance Characteristics (Continued) Figure7. Typical Holding Current vs Junction Temperature Figure8. Junction to Case Thermal Resistance 5 Junction to Case Thermal Resistance, [°C/W] 50 I_H[mA],Holding Current 40 3 30 Q3 2 20 Q1 Q2 10 0 L -40 0 🖵 1E-6 40 80 120 0 1E-5 1E-4 1E-3 0.01 0.1 1 T_[[°C], Junction Temperature Time, [S]

100

10



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